WHAT IS CLAIMED IS:

1. A chip device comprising:

a leadframe including a plurality of leads;

a die including a metallized backside and further including source and gate terminals opposite the metallized backside, the die being coupled to the leadframe such that the leads of the leadframe are directly coupled to the terminals; and

a body with a window defined therein, the body enveloping at least a portion of the leadframe and the die;

wherein the die is positioned with respect to the body such that the metallized backside is adjacent the window.

2. A chip device in accordance with claim 1 wherein the die is coupled to the leadframe with solder bumps.

3. A chip device in accordance with claim 1 wherein the leadframe is silver plated where the leadframe is coupled to the terminals.

4. A chip device in accordance with claim 1 wherein the leadframe is nickel plated where the leadframe is coupled to the terminals.

5. A chip device in accordance with claim 1 wherein the device comprises two dies each including a metallized backside and each further including source and gate terminals opposite the metallized backside, the dies being coupled to corresponding die attach pads of the leadframe such that the leads of the leadframe are directly coupled to the terminals, and wherein the body includes two windows defined therein and the dies are positioned with respect to the body such that the metallized backsides are adjacent a corresponding window.

6. A chip device in accordance with claim 5 wherein the die attach pads are coupled to one another.

7. A method of making a chip device, the method comprising:

providing a leadframe that includes leads;

providing a die that includes a metallized backside;

coupling the die to the leadframe; and

encapsulating the die with a body such that the metallized backside of the die is adjacent a window defined within the body.

8. A method in accordance with claim 7 further comprising configuring the plurality of leads.

9. A method in accordance with claim 8 further comprising removing dambars from the leadframe, removing mold flashes and resins from the leads, and solder plating the leads.

10. A method in accordance with claim 7 further comprising marking the body on a surface opposite the window.

11. A method in accordance with claim 10 wherein the marking is performed with a laser.

12. A method in accordance with claim 10 wherein the marking is performed with ink.

13. A method in accordance with claim 7 wherein the leadframe is provided with preplated leads.

14. A method in accordance with claim 7 wherein the leadframe is provided with preformed leads.

15. A method in accordance with claim 7 wherein the leadframe is provided with preplated leads and preformed leads.

16. A method in accordance with claim 7 wherein the die is coupled to the leadframe die attach pad and post via solder bumps, and wherein the solder bumps are re-flowed.

17. A method in accordance with claim 7 wherein the leadframe is provided with two die attach pads and posts, and the method further comprises providing two dies that each include a metallized back side, and coupling the first of the two dies to a first die attach pad and post, coupling a second of the two dies to a second die attach pad and post.